ANDO DK Co.,Ltd

Top
Corporate Profile
Product
Contact us
Japanese

Products Guide

Conductive
- AG-03X7
- AG-03LF3
- SND-AG
- AG-08F
- AG-03RP
- AG-03LMA
- AG-03HT
- AG-03LTX2
- FM23-79AG
- AG-03L
- AG-03LLF

Insulative
- Si-03LMA-D
- Si-03LMA-DS
- SND-SI
- SI-RP-27
- RLT-8412
- FM23-79SI

Under fill
- SI-03LMA-UZ6

Encapsulation
- EC-10X4
- EC-10FLP
- EC-10FLPW
- DAM-10
- CMOS-05
- PC-03
- FM23-79SIE

Clear Encapsulation
- CMOS-05
- PC-03

Optical Device
- CA-61
- OPD-11
- OPD-22N8
- OPD-11HC

Probing Ink
- MI-40B1

Die Attach Paste for General LSI

AG-03X7

Application

Die Attachment for General Purpose from LED to LSI devices.

features

Low ion content
Low modulus of elasticity (low warpage)
Low moisture absorption/ Suitable for reduction of soldering cracks of molded LSI
Versatility of dies and substrates

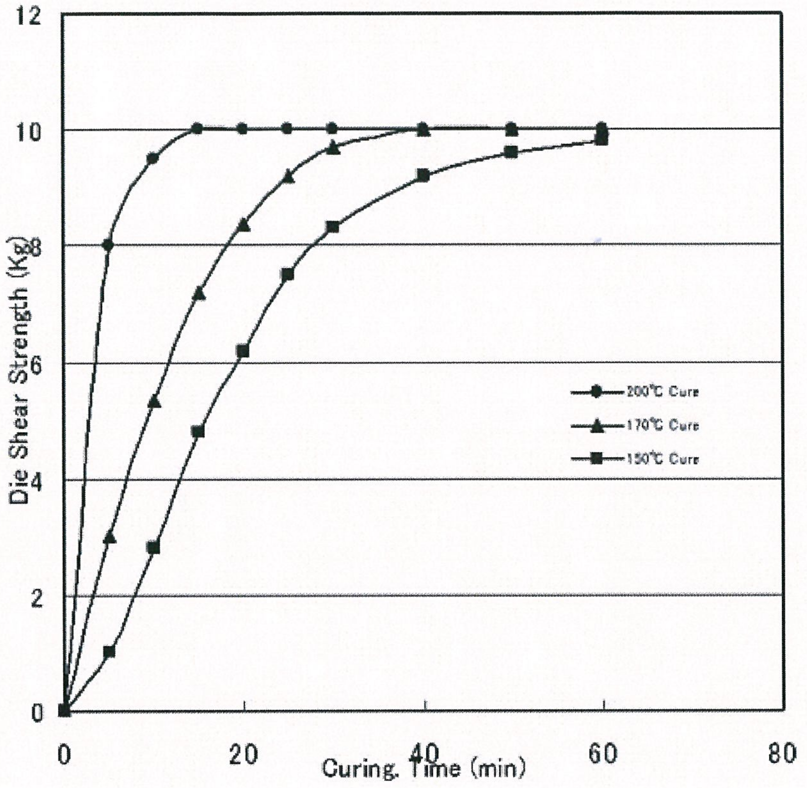
Typical Data

Major component	:	Epoxy resin/Acid Anhydride Hardener/Silver
Appearance	:	Silver Brownish paste
Viscosity @25℃	:	8000 cps
Gel time @175℃	:	20sec
Wt. Loss @260℃	:	0.2% (180℃/1hr cure)
Glass transition temperature	:	Tg$_1$: 57℃ Tg$_2$: 159℃ Tg$_3$: 317℃
CTE	:	28ppm(RT-57℃), 14ppm(57-159℃), 33ppm(159-317℃)
Modulus of elasticity	:	840MPa
Adhesive strength	:	Fig.1 (1.6 x 3.2 mm ceramic chip)
PCT. Die Shear Test	:	Fig.2
Properties of water extract>	:>	100 mesh PCT: 20hr,PH4.8, EC10micro s/cm>
Ionic Impurities	:	Cl: 1ppm, Na: 0.8ppm, K: 0.7ppm,
Water absorption	:	1.9% P.C.T. 168hr (see Fig.3)
Thermal conductivity	:	2w/m-k
Volume resistivity	:	2.0x10^{-4}Ω-cm
Shelf life @-20℃	:	6 month
Pot life @25℃	:	2days

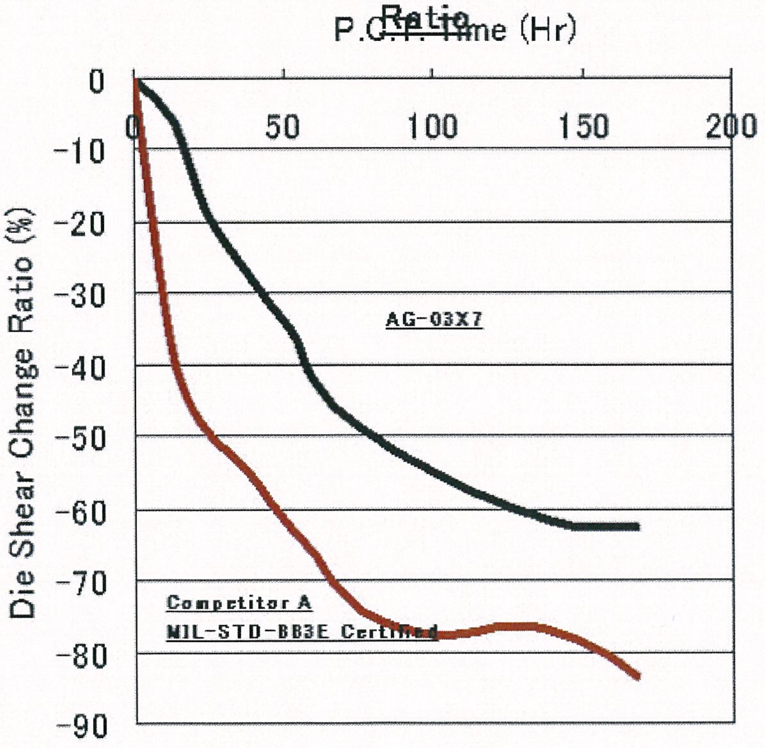
Cure Schedule/example

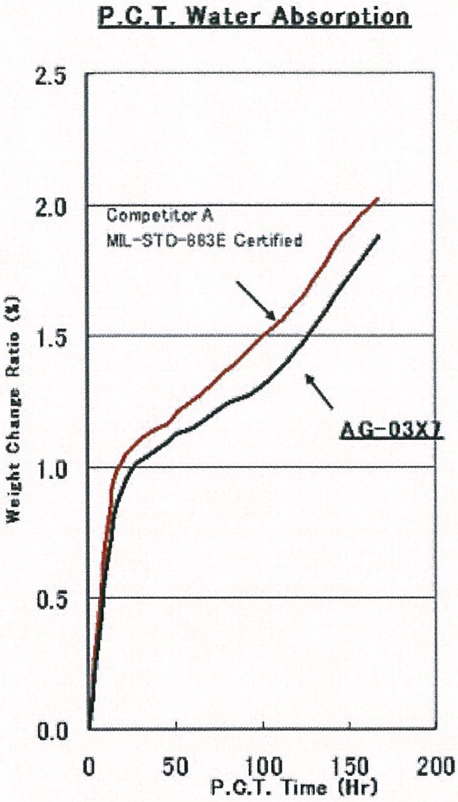
*1:@170℃/35min or longer

Die Shear Strength Vs.Curing Time at Varied Temperatures.



P.C.T. Die Shear Strength Change Ratio





P.C.T. Water Absorption